L Number	Hits	Search Text	DB	Time stamp
1	4		USPAT; US-PGPUB; EPO; JPO	2003/10/03 12:17
2	8	(385/\$).ccls. and optoelectronic and (compression near3 molding)	USPAT; US-PGPUB;	2003/10/03 12:17
3	95	((optic\$ or optoelectronic) near5 device) and substrate and (compres\$ near4 mold\$) and (curable or curing or epoxy or	EPO; JPO USPAT; US-PGPUB;	2003/10/03 12:18
4	425	mold\$) and (curable or curing or epoxy or plastic or fluid or	EPO; JPO USPAT; US-PGPUB;	2003/10/03 12:26
5	99	polymer) and (capsul\$ or encapsulat\$) optical and device and substrate and (curable or curing or epoxy or plastic or fluid or polymer) and (capsul\$ or encapsulat\$) and ((mold or molding or shape or shaping) near\$ tool) and (fiber or wavequide)	EPO; JPO USPAT; US-PGPUB; EPO; JPO	2003/10/03 12:28
6	135		USPAT; US-PGPUB; EPO; JPO	2003/10/03 12:29
7	5	(385/88,89,94).ccls. and optical and device and substrate and (curable or curing or epoxy or plastic or fluid or polymer) and (capsuls or encapsulats) and ((mold or molding or shape or shaping) near5 tool) and (fiber or	USPAT; US-PGPUB; EPO; JPO	2003/10/03 12:32
8	2	waveguide) ((385/88,89,94).ccls. or (372/50).ccls.) and optical and device and (curable or curing) and (epoxy or plastic or resin or polymer) and (fluid or gel) and (capsul\$ or encapsulat\$) and ((mold or molding or shape or shaping) near\$ tool) and (fiber or waveguide)	USPAT; US-PGPUB; EPO; JPO	2003/10/03 12:33
9	4	((385/88,89,94).ccis. or (372/50).ccis.) and optical and device and (curable or curing) and (epoxy or plastic or resin or polymer) and (fluid or gel) and (capsul\$ or encapsulat\$)	USPAT; US-PGPUB; EPO; JPO	2003/10/03 12:33
10	12	and (mold or molding or shape or shaping) and vcsel ((385/88,89,94).ccls. or (372/50).ccls.) and optical and device and (curable or curing) and (epoxy or plastic or resin or polymer) and (fluid or gel) and (capsul\$ or encapsulat\$)	USPAT; US-PGPUB; EPO; JPO	2003/10/03 12:3:
11	39	and (mold or molding or shape or shaping) ((385/88,89,94).ccls. or (372/50).ccls.) and optical and device and (curable or curing) and (epoxy or plastic or resin or fluid or gel) and (capsul\$ or encapsulat\$) and (mold or	USPAT; US-PGPUB; EPO; JPO	2003/10/03 12:3
12	7	molding or shape or shaping) device and encapsulat\$ and (cure or curable or curing) and optical	EPO; JPO	2003/10/03 12:3
13	36	device and encapsulat\$ and (cure or curable or curing) and optical	DERWENT	2003/10/03 12:3
14	63	device and (shap\$ near4 encapsulat\$) and (cure or curable or curing) and optical	USPAT; US-PGPUB	2003/10/03 12:36
15	253	device and (mold\$ near4 encapsulat\$) and (cure or curable or curing) and optical	USPAT; US-PGPUB	2003/10/03 12:38
16	246	device and (molds near4 encapsulats) and (cure or curable or curing) and optical and (gel or epoxy or adhesive or fluid or polymer)	USPAT; US-PGPUB	2003/10/03 14:02
17	350		USPAT; US-PGPUB	2003/10/03 14:12
18	15	(compression near4 molding) and (cure or curing or curable) and encapsula\$ and optoelectronic and fiber	USPAT; US-PGPUB; EPO; JPO	2003/10/03 14:23

19	21	(compression near4 molding) and (cure or curing or curable)	USPAT;	2003/10/03 14:24
1	İ	and encapsula\$ and (optic\$ near5 electronic) and fiber	US-PGPUB;	į
		l <u></u>	EPO; JPO	
20	5	(385/94).ccls. and (mold\$ or shape or shaping) and (curable	USPAT;	2003/10/03 14:24
i		or curing or epoxy or plastic or fluid or polymer) and	US-PGPUB;	
	1	(capsul\$ or encapsulat\$) and tool	EPO; JPO	1
21	37	(385/94).ccls. and (mold\$ or shape or shaping) and (curable	USPAT:	2003/10/03 14:25
1	1	or curing or epoxy or plastic or fluid or polymer) and	US-PGPUB:	
		(capsul\$ or encapsulat\$)	EPO; JPO	